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STGB30H65FB

Trench gate field-stop IGBT, HB series 650 V, 30 A high speed in a D²PAK package

Datasheet - production data

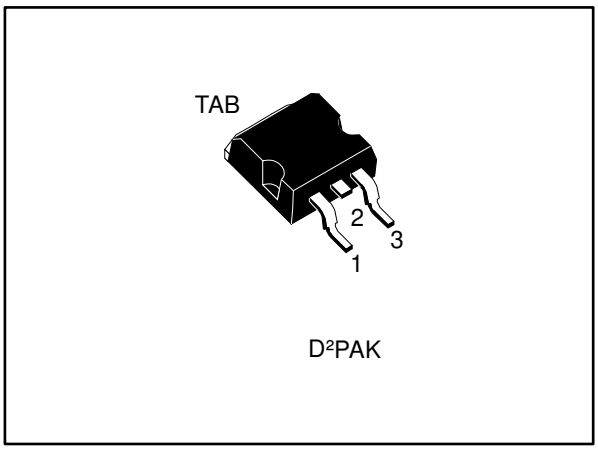
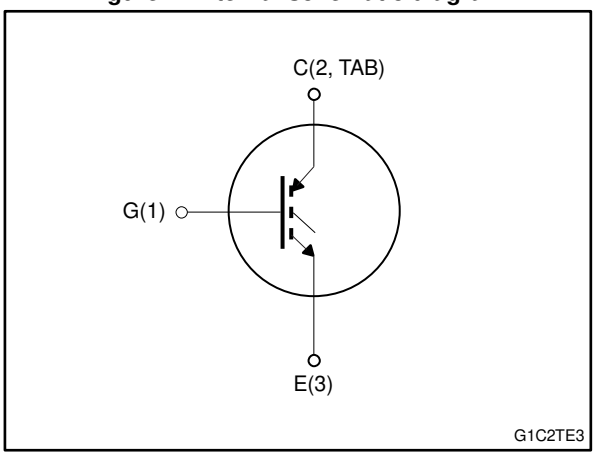


Figure 1: Internal schematic diagram



Features

- Maximum junction temperature: T_J = 175 °C
- High speed switching series
- Minimized tail current
- $V_{CE(sat)}$ = 1.55 V(typ.) @ I_C = 30 A
- Safe paralleling
- Tight parameter distribution
- Low thermal resistance

Applications

- Photovoltaic inverters
- High frequency converters

Description

This device is an IGBT developed using an advanced proprietary trench gate field-stop structure. The device is part of the new HB series of IGBTs, which represents an optimum compromise between conduction and switching loss to maximize the efficiency of any frequency converter. Furthermore, the slightly positive $V_{CE(sat)}$ temperature coefficient and very tight parameter distribution result in safer paralleling operation.

Table 1: Device summary

Order code	Marking	Package	Packing
STGB30H65FB	GB30H65FB	D²PAK	Tape and reel

Contents

1 Electrical ratings 3
2 Electrical characteristics 4
2.1 Electrical characteristics (curves) 6
3 Test circuits 10
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1 Electrical ratings

Table 2: Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{CES}	Collector-emitter voltage (V_{GE} = 0 V)	650	V
I_C	Continuous collector current at T_C = 25 °C	60	A
	Continuous collector current at T_C = 100 °C	30	
I_{CP}(1)	Pulsed collector current	120	A
V_{GE}	Gate-emitter voltage	±20	V
P_{TOT}	Total dissipation at T_C = 25 °C	260	W
T_{STG}	Storage temperature range	- 55 to 150	°C
T_J	Operating junction temperature range	- 55 to 175	

Notes:

(1)Pulse width limited by maximum junction temperature.

Table 3: Thermal data

Symbol	Parameter	Value	Unit
R_{thJC}	Thermal resistance junction-case	0.58	°C/W
R_{thJA}	Thermal resistance junction-ambient	62.5	

2 Electrical characteristics

T_C = 25 °C unless otherwise specified

Table 4: Static characteristics

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)CES}$	Collector-emitter breakdown voltage	V_{GE} = 0 V, I_C = 2 mA	650			V
$V_{CE(sat)}$	Collector-emitter saturation voltage	V_{GE} = 15 V, I_C = 30 A		1.55	2	V
		V_{GE} = 15 V, I_C = 30 A, T_J = 125 °C		1.65		
		V_{GE} = 15 V, I_C = 30 A, T_J = 175 °C		1.75		
$V_{GE(th)}$	Gate threshold voltage	V_{CE} = V_{GE}, I_C = 1 mA	5	6	7	V
I_{CES}	Collector cut-off current	V_{GE} = 0 V, V_{CE} = 650 V			25	µA
I_{GES}	Gate-emitter leakage current	V_{CE} = 0 V, V_{GE} = ±20 V			±250	nA

Table 5: Dynamic characteristics

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{ies}	Input capacitance	V_{CE}= 25 V, f = 1 MHz, V_{GE} = 0 V	-	3659	-	pF
C_{oes}	Output capacitance		-	101	-	
C_{res}	Reverse transfer capacitance		-	76	-	
Q_g	Total gate charge	V_{CC} = 520 V, I_C = 30 A, V_{GE} = 0 to 15 V (see *Figure 23: "Gate charge test circuit"*)	-	149	-	nC
Q_{ge}	Gate-emitter charge		-	25	-	
Q_{gc}	Gate-collector charge		-	62	-	

Table 6: IGBT switching characteristics (inductive load)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	V_{CE} = 400 V, I_C = 30 A, V_{GE} = 15 V, R_G = 10 Ω (see *Figure 22: "Test circuit for inductive load switching"*)	-	37	-	ns
t_r	Current rise time		-	14.6	-	
$(di/dt)_{on}$	Turn-on current slope		-	1643	-	A/µs
$t_{d(off)}$	Turn-off-delay time		-	146	-	ns
t_f	Current fall time		-	23	-	
E_{on}(1)	Turn-on switching energy		-	151	-	µJ
E_{off}(2)	Turn-off switching energy		-	293	-	
E_{ts}	Total switching energy		-	444	-	
$t_{d(on)}$	Turn-on delay time	V_{CE} = 400 V, I_C = 30 A, V_{GE} = 15 V, R_G = 10 Ω, T_J = 175 °C (see *Figure 22: "Test circuit for inductive load switching"*)	-	35	-	ns
t_r	Current rise time		-	16.1	-	
$(di/dt)_{on}$	Turn-on current slope		-	1496	-	A/µs
$t_{d(off)}$	Turn-off-delay time		-	158	-	ns
t_f	Current fall time		-	65	-	
E_{on}(1)	Turn-on switching energy		-	175	-	µJ
E_{off}(2)	Turn-off switching energy		-	572	-	
E_{ts}	Total switching energy		-	747	-	

Notes:

(1)Including the reverse recovery of the diode. Turn-on times and energy have been measured applying as freewheeling an external SiC diode STPSC206W.

(2)Including the tail of the collector current.

2.1 Electrical characteristics (curves)

Figure 2: Output characteristics (T_J = 25 °C)

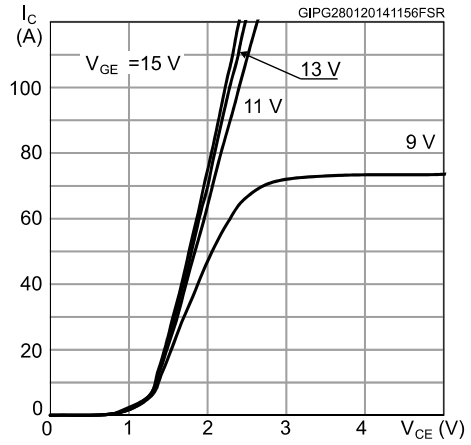


Figure 3: Output characteristics (T_J = 175 °C)

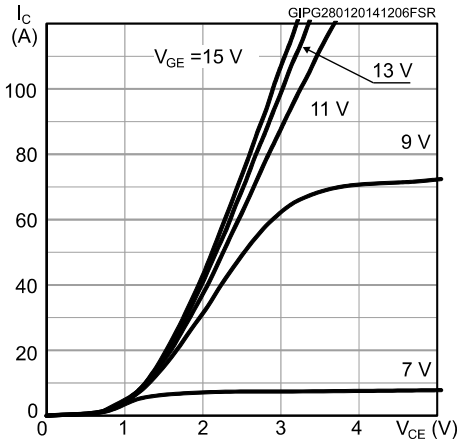


Figure 4: Transfer characteristics

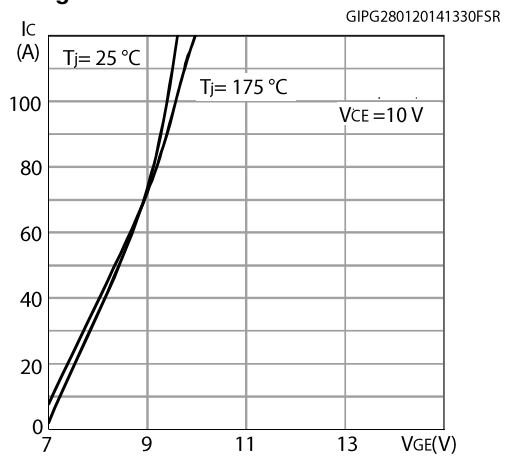


Figure 5: Collector current vs. case temperature

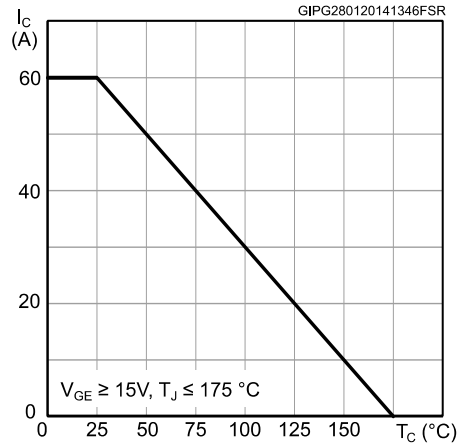


Figure 6: $V_{CE(sat)}$ vs. junction temperature

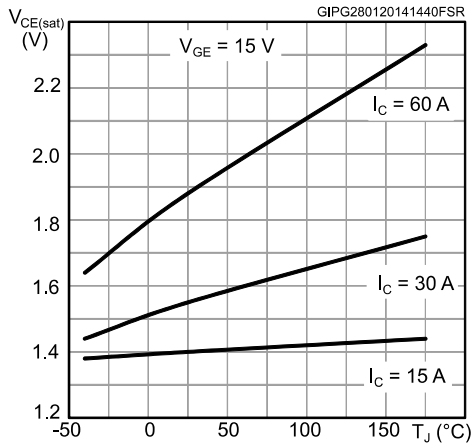


Figure 7: Power dissipation vs. case temperature

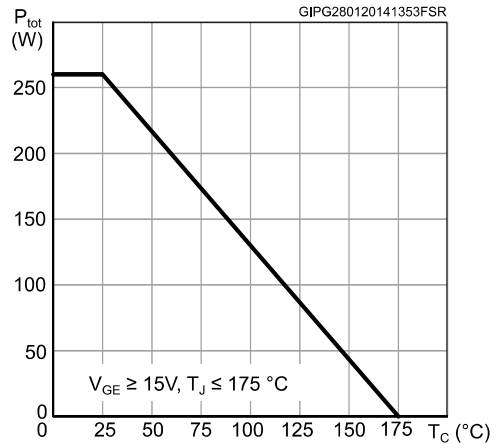


Figure 8: Forward bias safe operating area

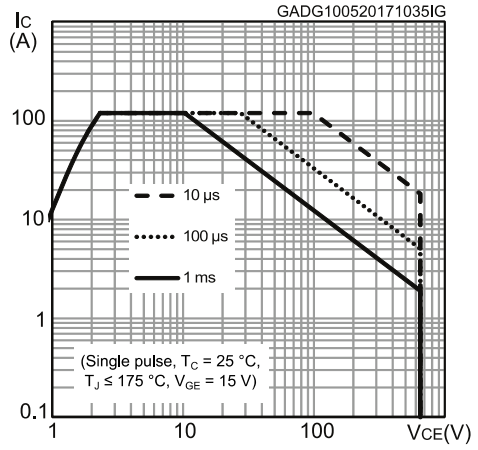


Figure 9: Collector current vs. switching frequency

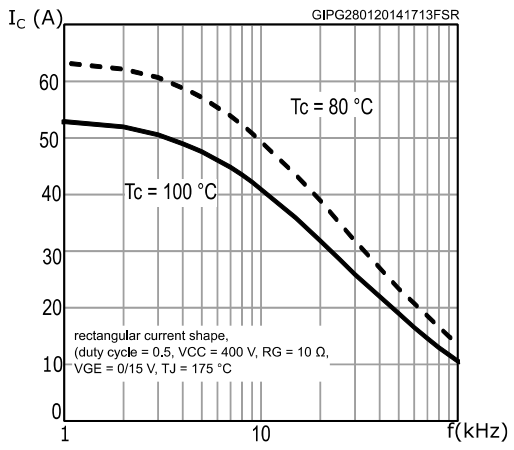


Figure 10: Normalized $V_{GE(th)}$ vs. junction temperature

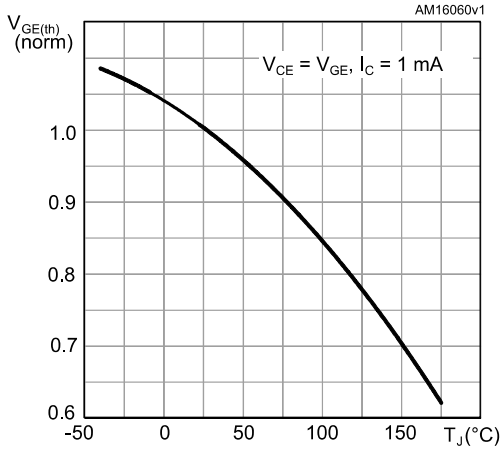


Figure 11: Normalized $V_{(BR)CES}$ vs. junction temperature

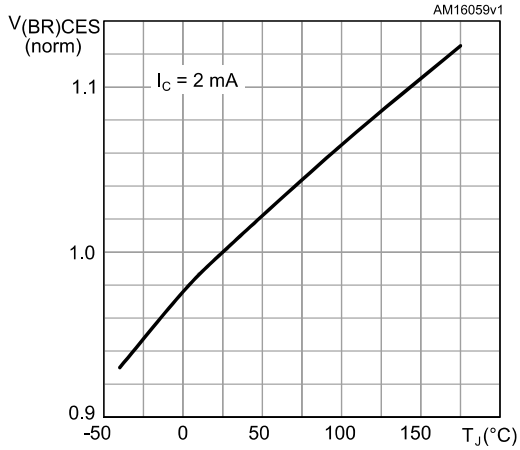


Figure 12: Switching energy vs. temperature

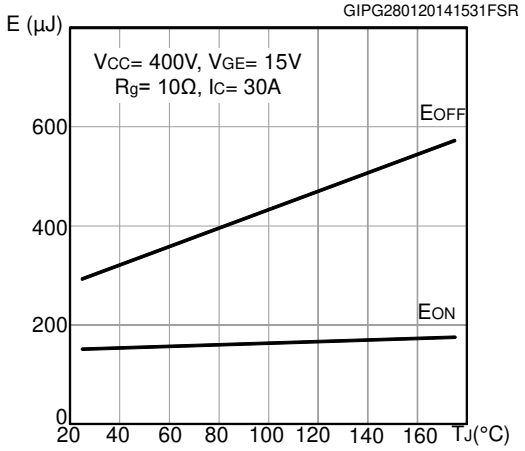


Figure 13: Switching energy vs. gate resistance

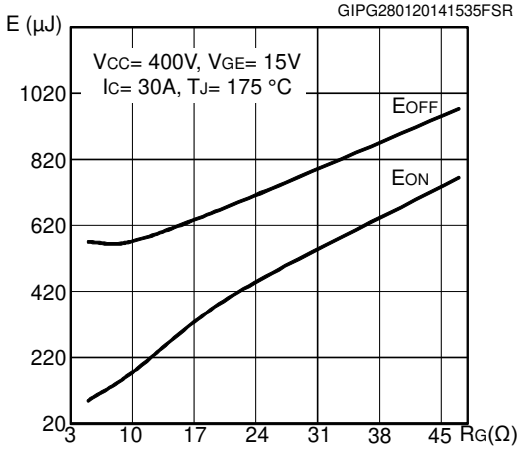


Figure 14: Switching energy vs. collector current

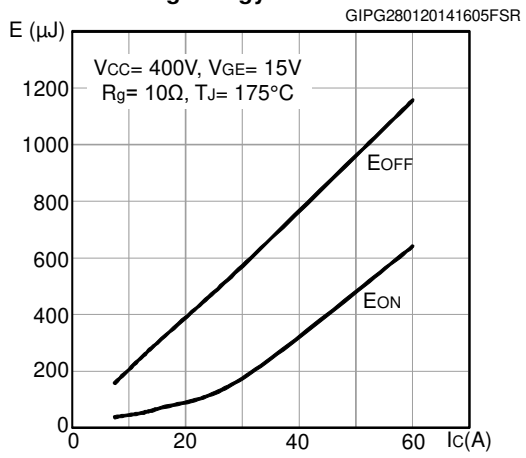


Figure 15: Switching energy vs. collector emitter voltage

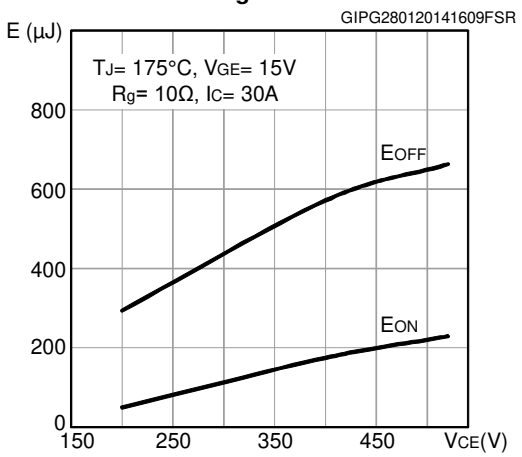


Figure 16: Switching times vs. collector current

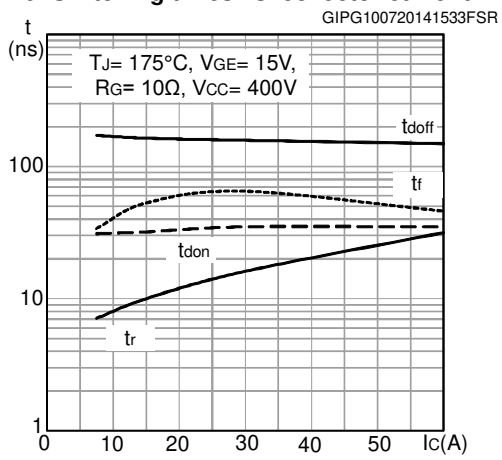


Figure 17: Switching times vs. gate resistance

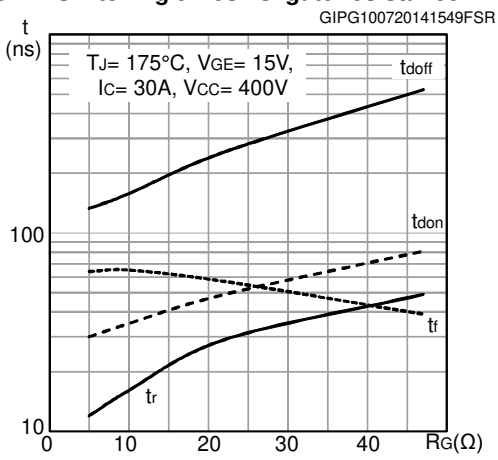


Figure 18: Capacitance variations

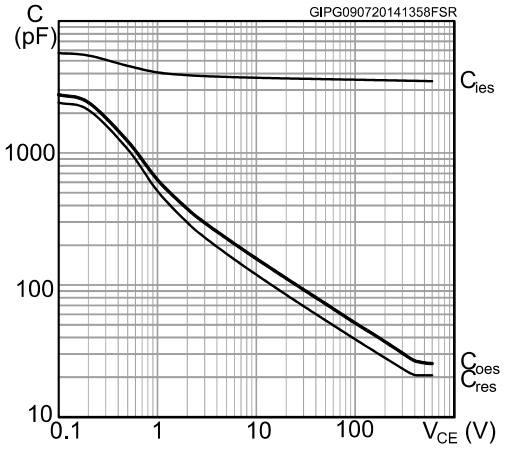


Figure 19: $V_{CE(sat)}$ vs. collector current

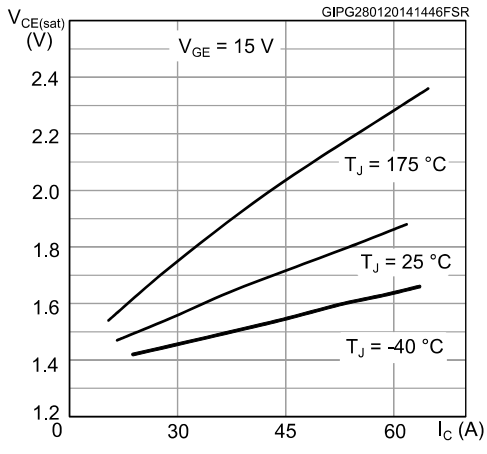


Figure 20: Gate charge vs. gate-emitter voltage

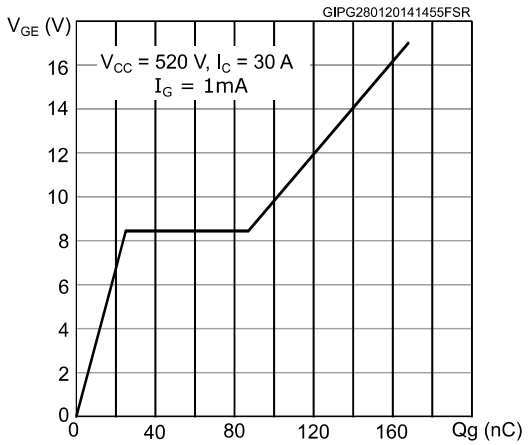
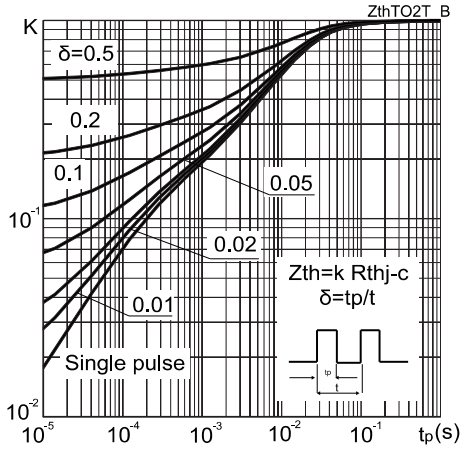


Figure 21: Thermal impedance



3 Test circuits

Figure 22: Test circuit for inductive load switching

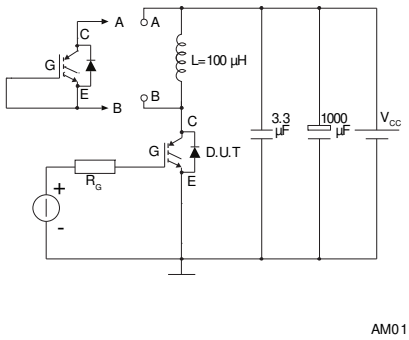


Figure 23: Gate charge test circuit

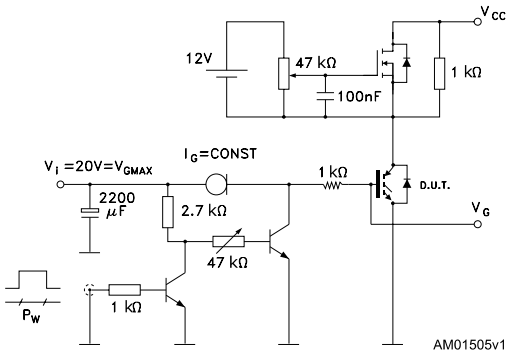
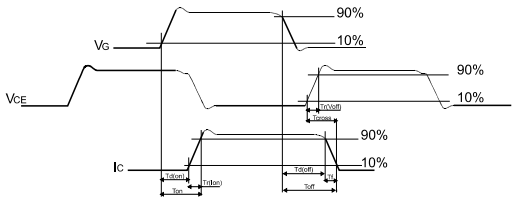


Figure 24: Switching waveform



4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: ***www.st.com***. ECOPACK® is an ST trademark.

4.1 D²PAK package information

Figure 25: D²PAK (TO-263) type A package outline

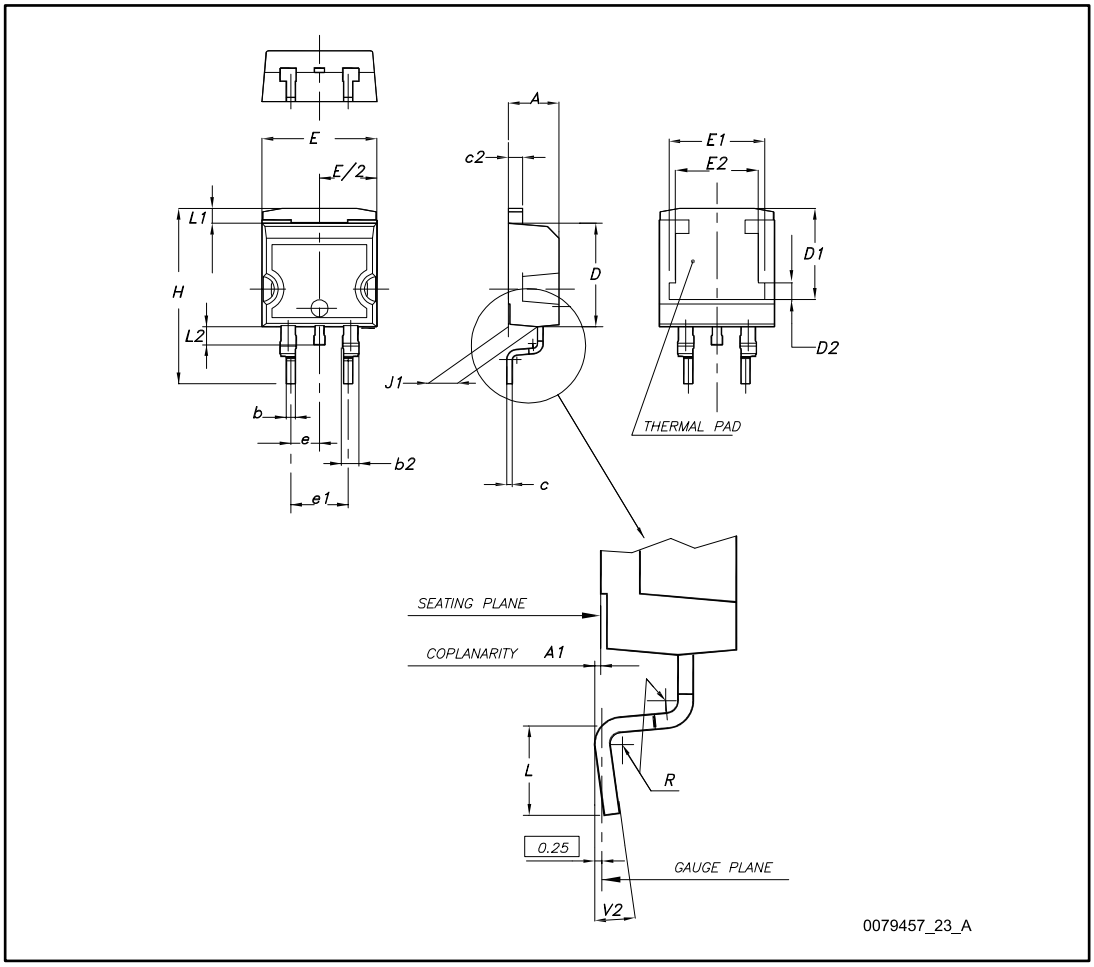
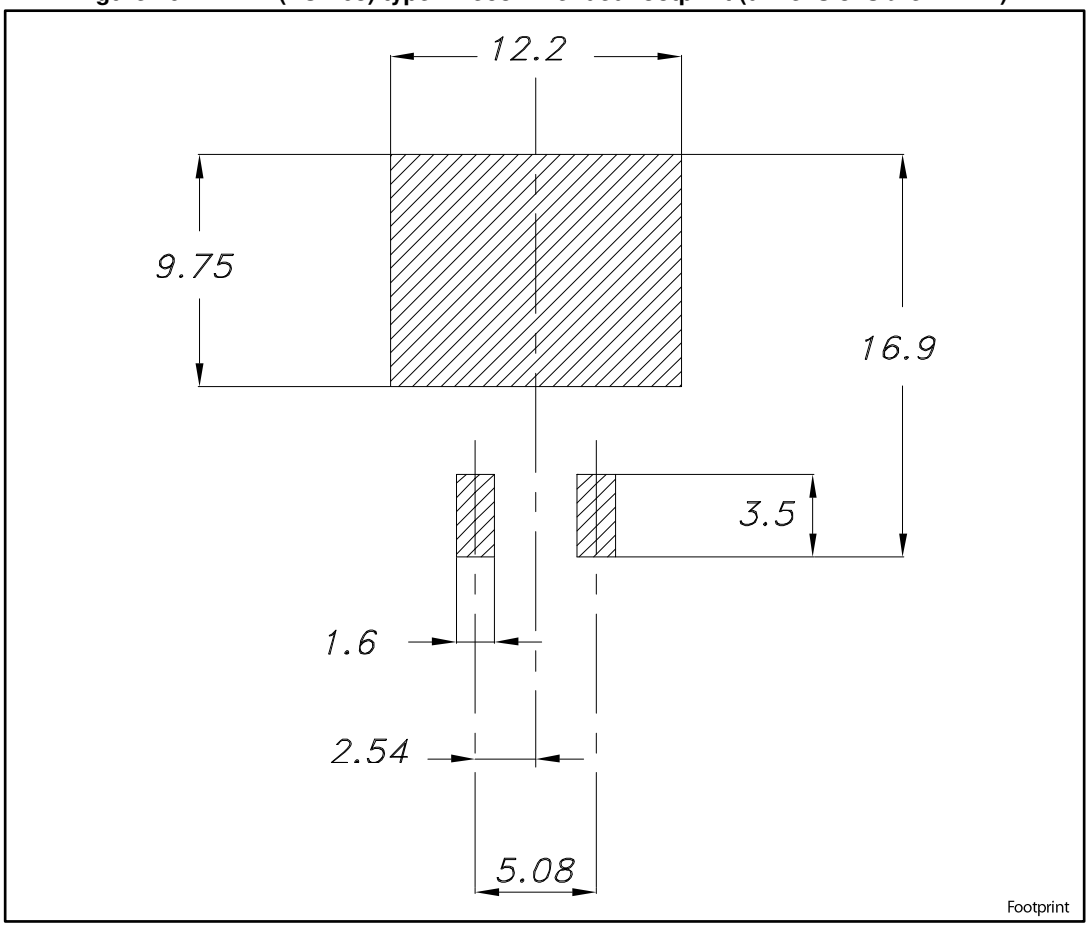


Table 7: D²PAK (TO-263) type A package mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
A1	0.03		0.23
b	0.70		0.93
b2	1.14		1.70
c	0.45		0.60
c2	1.23		1.36
D	8.95		9.35
D1	7.50	7.75	8.00
D2	1.10	1.30	1.50
E	10.00		10.40
E1	8.50	8.70	8.90
E2	6.85	7.05	7.25
e		2.54	
e1	4.88		5.28
H	15.00		15.85
J1	2.49		2.69
L	2.29		2.79
L1	1.27		1.40
L2	1.30		1.75
R		0.40	
V2	0°		8°

Figure 26: D²PAK (TO-263) type A recommended footprint (dimensions are in mm)



4.2 D²PAK packing information

Figure 27: D²PAK type A tape outline

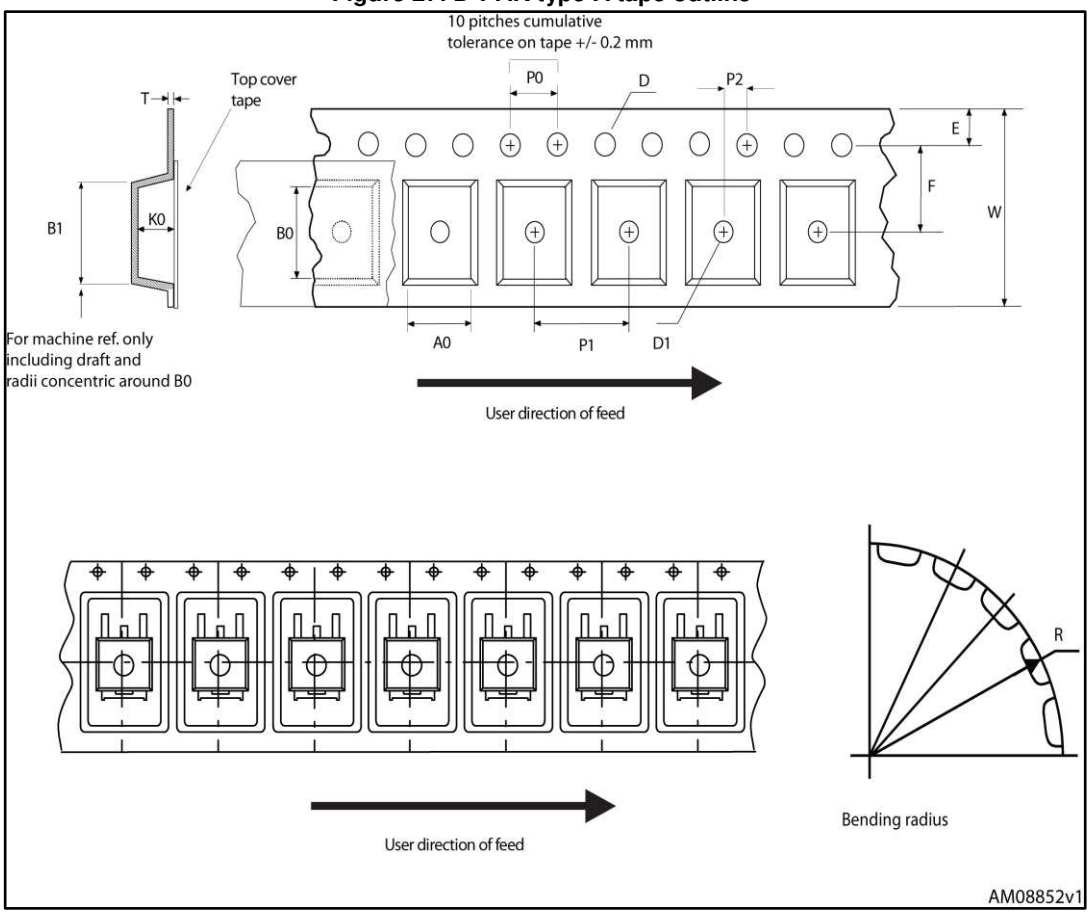


Figure 28: D²PAK type A reel outline

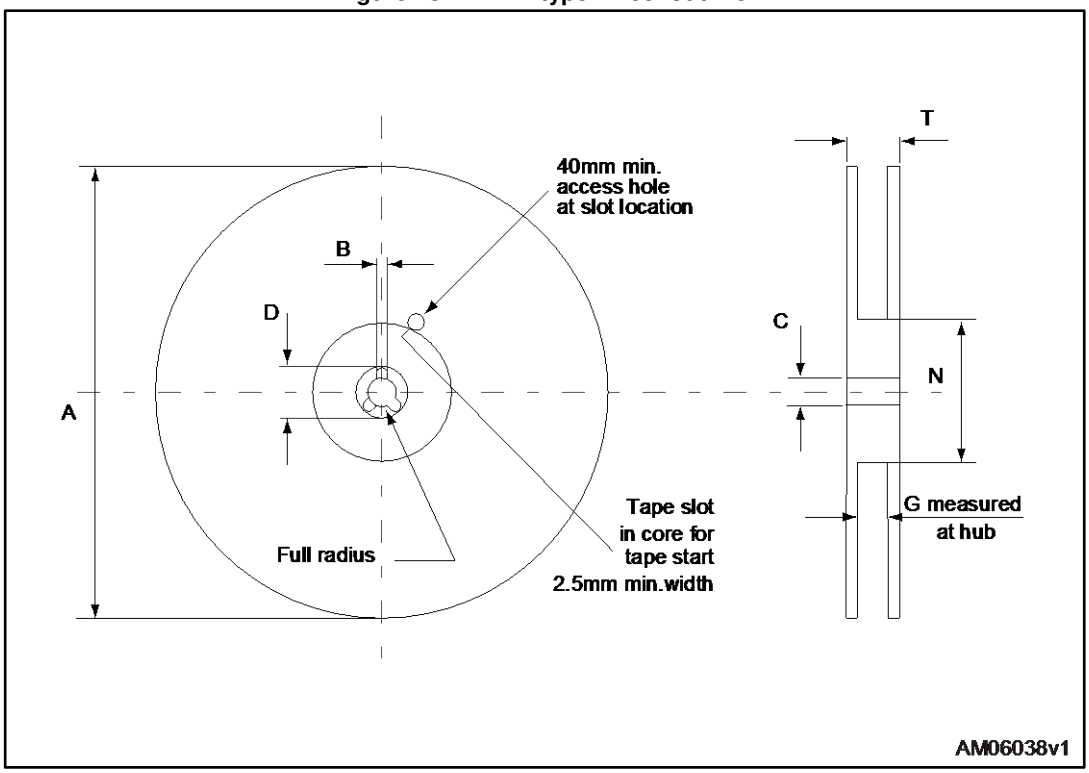


Table 8: D²PAK type A tape and reel mechanical data

Tape			Reel		
Dim.	mm		Dim.	mm	
	Min.	Max.		Min.	Max.
A0	10.5	10.7	A		330
B0	15.7	15.9	B	1.5	
D	1.5	1.6	C	12.8	13.2
D1	1.59	1.61	D	20.2	
E	1.65	1.85	G	24.4	26.4
F	11.4	11.6	N	100	
K0	4.8	5.0	T		30.4
P0	3.9	4.1			
P1	11.9	12.1	Base quantity		1000
P2	1.9	2.1	Bulk quantity		1000
R	50				
T	0.25	0.35			
W	23.7	24.3			

5 Revision history

Table 9: Document revision history

Date	Revision	Changes
11-May-2017	1	Initial release.
29-May-2017	2	Document status promoted from preliminary to production data.

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